

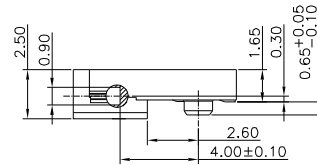
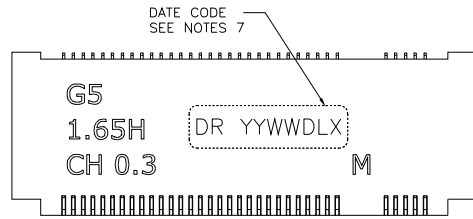
**HF**

Halogen Free



1 2 3 4 5 6 7 8

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1	NA	NA	INITIAL RELEASE	2022.11.28	Jason Huang



NOTES:  
PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0

1. MATERIAL:

1.1 HOUSING: LCP , UL94V-0; COLOR: BLACK

1.2 CONTACTS: PHOSPHOR BRONZE

1.3 FLOATING PEG: STAINLESS STEEL

1.4 CENTER PLATE: STAINLESS STEEL

2. FINISH:

2.1 CONTACT:

CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER,

Au GF PLATING ON SOLDERTAIL. GOLD PLATING

(THICKNESS SEE NOTE 10) ON CONTACT AREA.

2.2 FLOATING PEG:

100u" MIN. MATTE-TIN. 50u"MIN. NICKEL UNDERPLATING.

3. REFLOW SOLDER CAPABLE TO 260°C 10SEC.

4. ELECTRICAL CHARACTERISTICS:

4.1 CONTACT CURRENT RATING: 0.5 AMPERE MAX, PER PIN,

4.2 VOLTAGE RATING: 50V AC.

4.3 INSULATION RESISTANCE: 500M OHM MIN.(INITIAL),

100M OHM MIN.(FINAL), AT 500V DC,

FOR 1 MINUTE.

4.5 CONTACT RESISTANCE: 55m OHM MAX(INITIAL)

ΔR 20m OHM MAX(FINAL)

5. OPERATION TEMPERATURE: -40°C TO +80°C

6. MATING FORCE: 2.04Kgf MAX.

DURABILITY: 60 CYCLES

7. DATE CODE YYWDLX

YY: YEAR (09: 2009)

WW: WEEK (25: THE 25TH WEEK)

D: DAY (1~7: SUNDAY~SATURDAY)

L: LINE NUMBER OF ASSEMBLY (A: LINE A)

X: MANUFACTURE CODE

8. CONNECTOR ACTUAL PIN QUANTITY IS 67, AS THE KEY TAKING OUT 8 PINS.

9. RECOMMENDED STENCIL THICKNESS 0.12MM MIN

10. PART NUMBER DESCRIPTION:

5621D3-027H - X B O R

PACKING CODE:

R: EMBOSS WIDTH 44mm, SLOT FORWARD

RESERVED: 0

KEY TYPE: B: KEY M

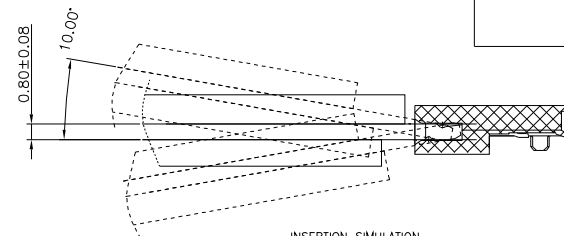
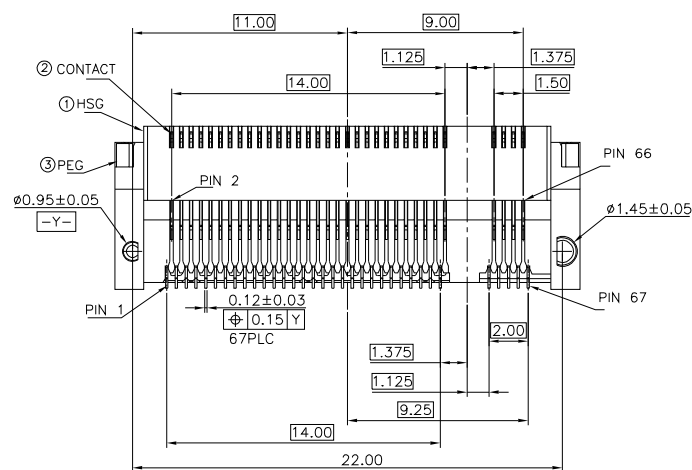
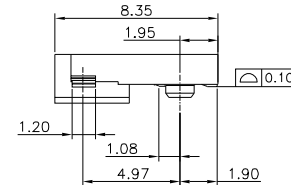
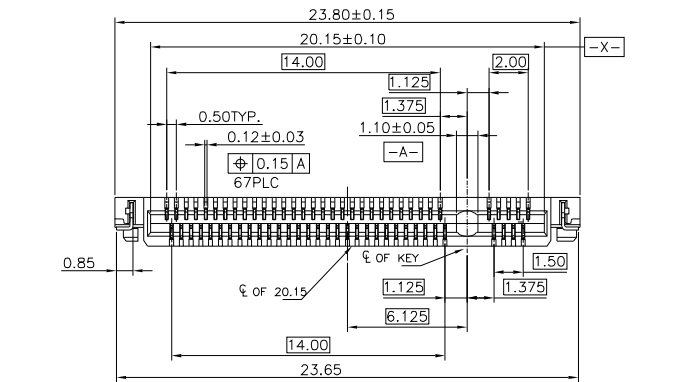
PLATING CODE:

1: GF 2: Au5u"

3: Au10u" 4: Au15u"

5: Au30u"

HALOGEN CODE: H: HALOGEN FREE



DIM	TOL	DIM	TOL
x.	±0.30	x.	±2'
.x	±0.25	.x	±1'
.xx	±0.15		

**DEREN**

SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.  
SC2208629

REV. X1

CUSTOMER DRAWING

DESIGN: Jason Huang

CHECK: Mike Chen

APPROVAL: Bill Lin

DATE

2022.11.28

2022.11.28

2022.11.28

TITLE: M.2 GEN5 1.65H CH 0.3mm

KEY M Dual SMT Type

P/N: SEE NOTE 10

SHEET: 1/3

SCALE: 1:1

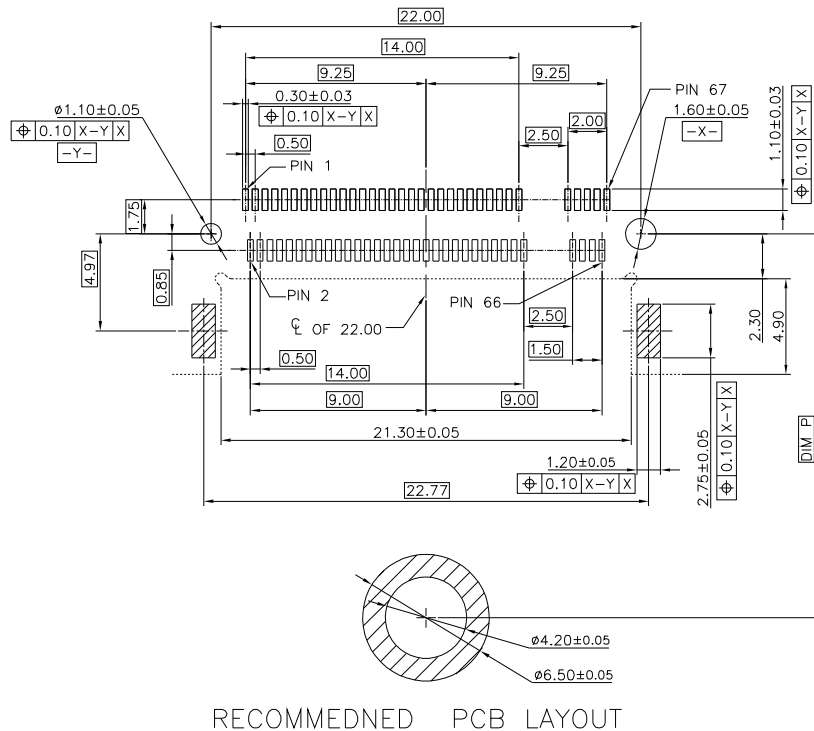
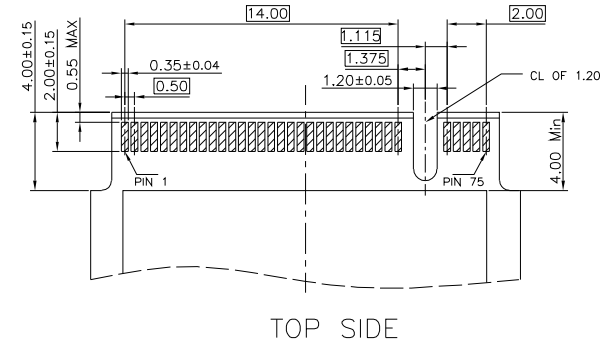
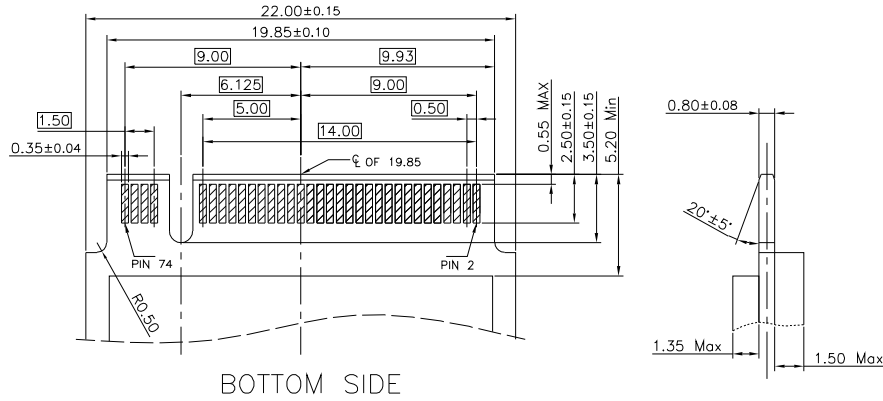
UNIT: mm

1 2 3 4 5 6 7 8

**HF**  
Hologen Free

PLUG PCB

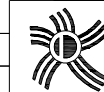
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
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RECOMMENDED PCB LAYOUT

22110	114.00
2280	84.00
2260	64.00
2242	46.00
2230	34.00
3042	46.00
3030	34.00
MOUDLE TYPE	DIM P

DIM	TOL	DIM	TOL
.x	±0.30	.x	±2'
.x	±0.25	.x	±1'
.xx	±0.15		

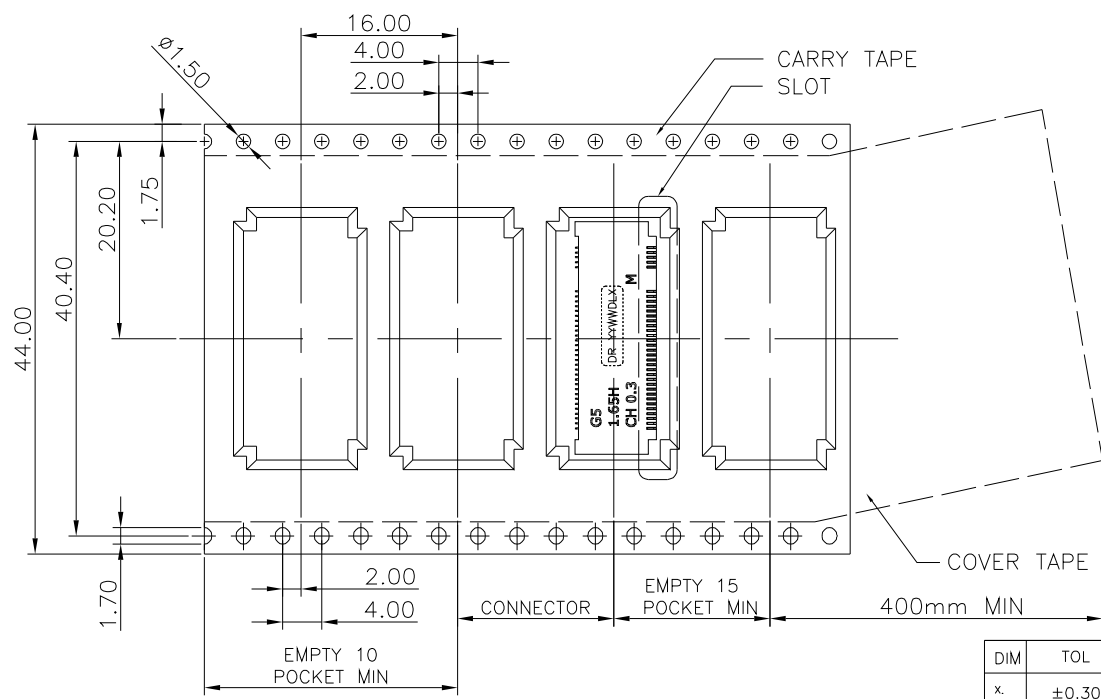
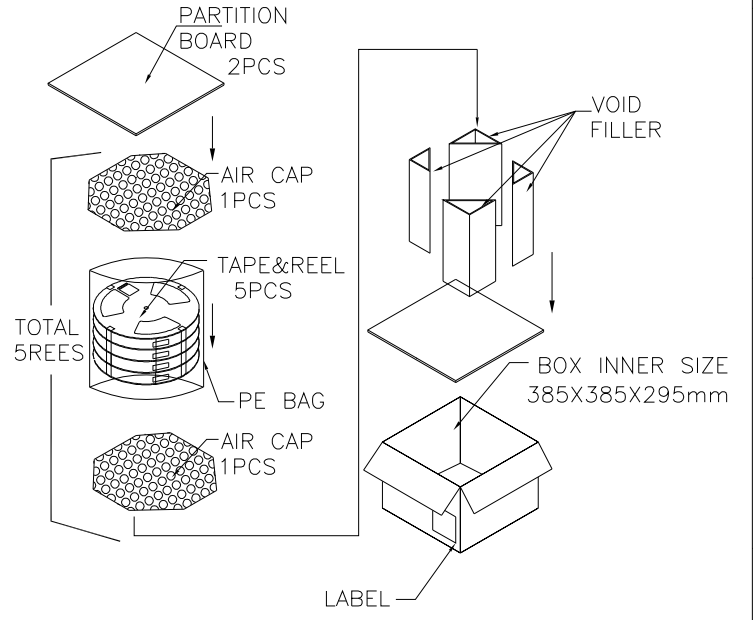
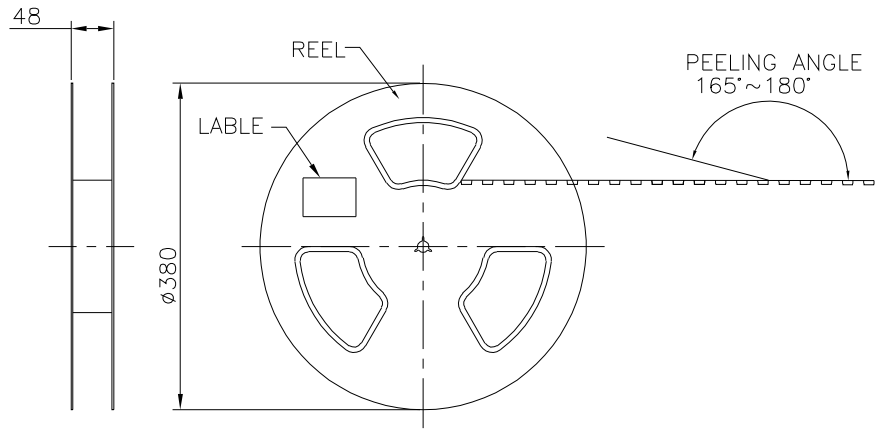


**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING	DATE	TITLE
DESIGN: Jason Huang	2022.11.28	M.2 GEN5 1.65H CH 0.3mm KEY M Dual SMT Type
CHECK: Mike Chen	2022.11.28	P/N: SEE NOTE 10
REV. X1	APPROVAL: Bill Lin	2022.11.28
		SHEET: 2/3
		SCALE: 1:1
		UNIT: mm



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1	NA	NA	INITIAL RELEASE	2022.11.28	Jason Huang



1500	5	7500
PCS/REEL	REELS/BOX	PCS/BOX

DIM	TOL	DIM	TOL
.x	±0.30	.x	±2'
.x	±0.25	.x	±1'
.xx	±0.15		



<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD			
CUSTOMER DRAWING		DATE	TITLE: M.2 GEN5 1.65H CH 0.3mm KEY M Dual SMT Type
DESIGN:	Jason Huang	2022.11.28	P/N: SEE NOTE 10
CHECK:	Mike Chen	2022.11.28	SHEET: 3/3
REV. X1	APPROVAL: Bill Lin	2022.11.28	SCALE: N/A UNIT: mm

1 2 3 4 5 6 7 8

A B C D E